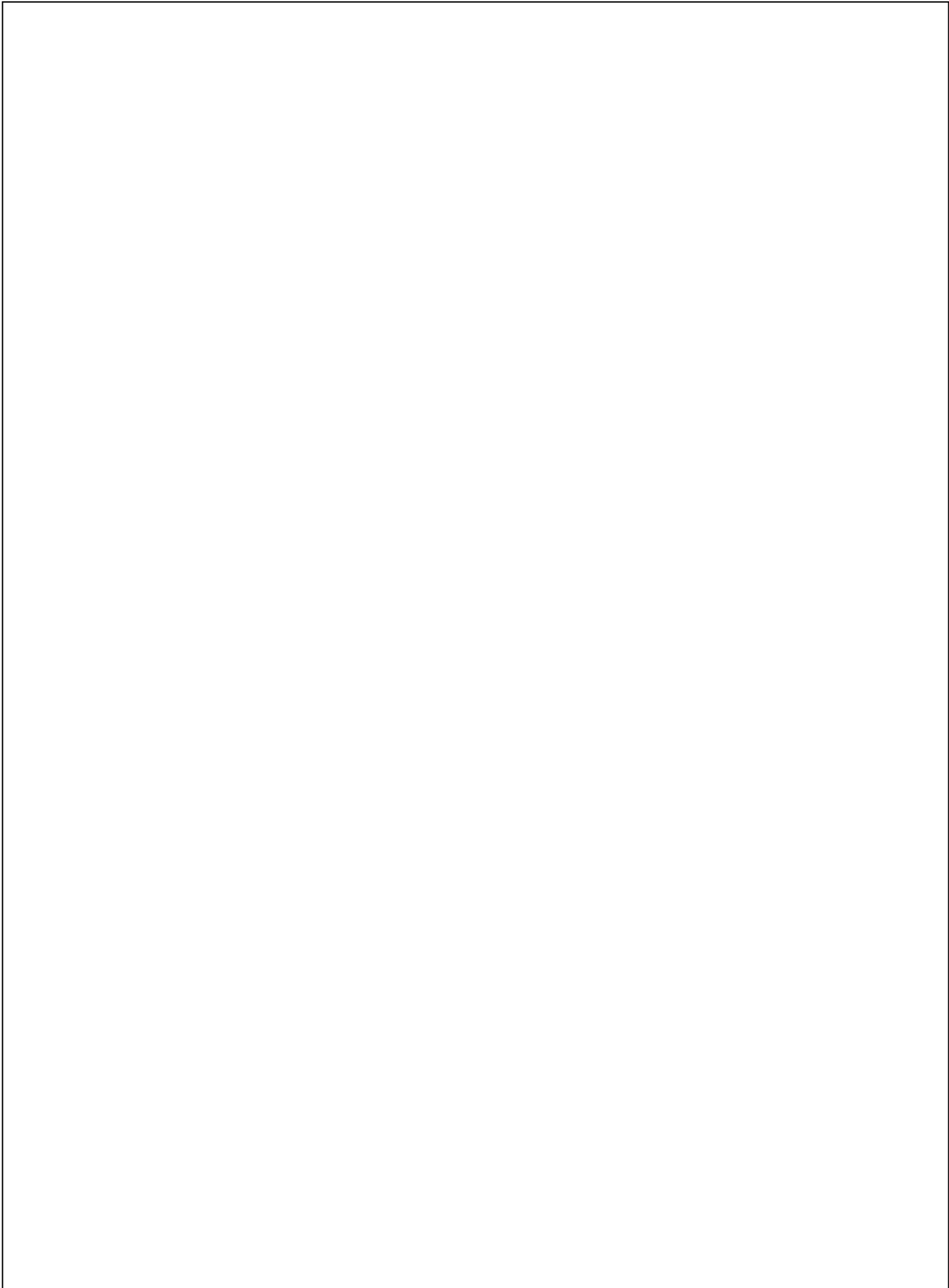


LIGHT





Electrical Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiant Intensity	I _e	2.2	3.0	4.4	mW/sr	I _F =20mA (Note 1,3)
Viewing Angle	$\frac{1}{2}$	---	130	---	Deg.	(Note 2)
Peak Wavelength		---	940	---	nm	I _F =20mA
Spectral Line Half- Width		---	50	---	nm	I _F =20mA
Forward Voltage	V _F	---	1.25	1.60	V	I _F =50mA
Reverse Current	I _R	---	---	100	μA	V _R =5V

Note:

- Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
- $\frac{1}{2}$ is the off-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.
- The I_e guarantee should be added ±15% tolerance.

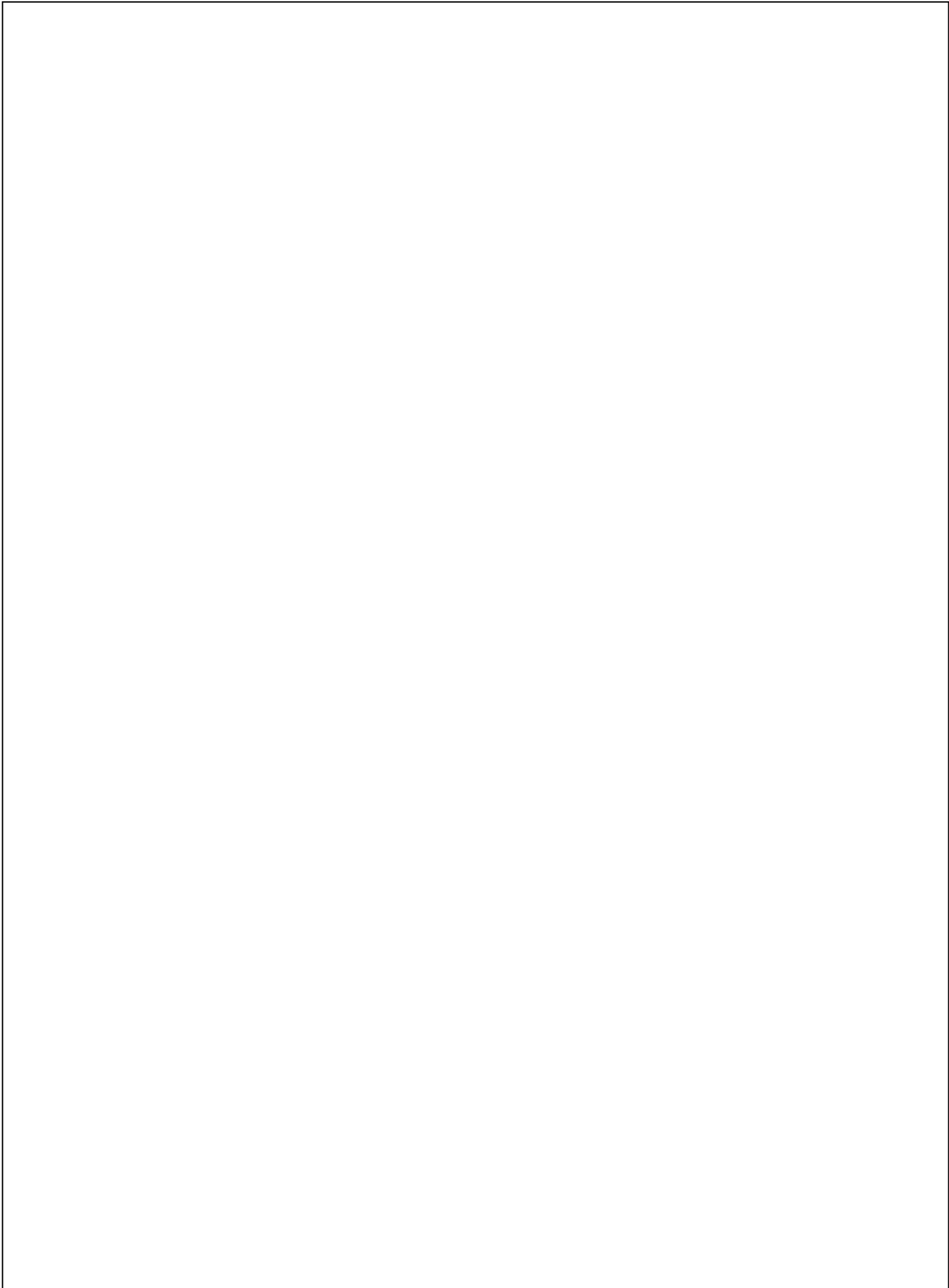
Infrared Emitting Diode Specification

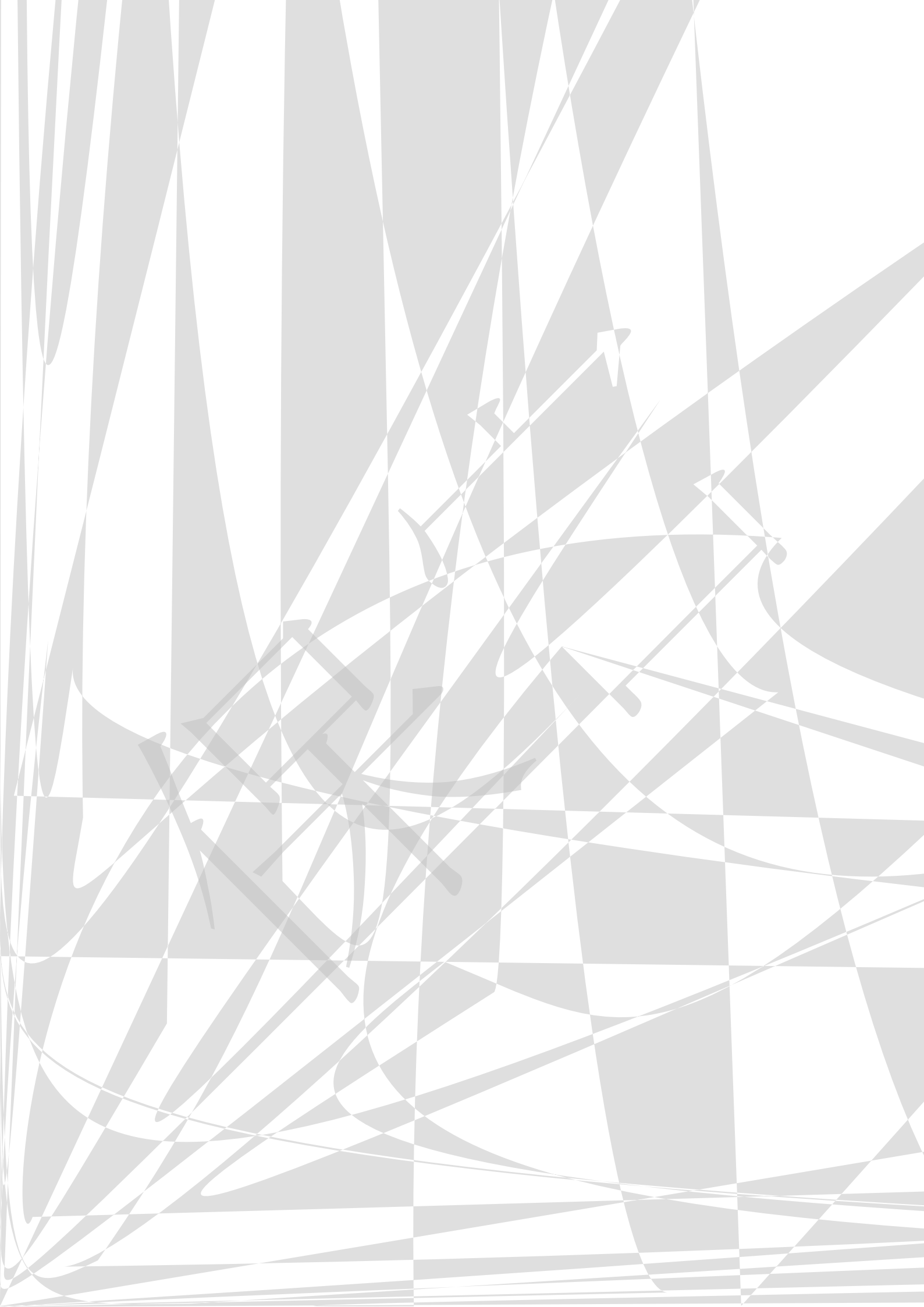
●Commodity: Infrared emitting diode

●Intensity Bin Limits (At 20mA)

BIN CODE	Min. (mW/sr)	Max. (mW/sr)
18	2.2	2.6
19	2.6	3.1
20	3.1	3.7
21	3.7	4.4

NOTE: The I_e guarantee should be added ±15% tolerance.





LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

